CC2541 Errata Note

This document provides updated information about known issues of the CC2541 system-on-chip (SoC).

1 Known Issues

Table 1 lists the known issues.

Table 1. Summary of Known Issues

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<td>Leaving PM2 or PM3 can produce glitches on the SCL and SDA pins.</td>
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1.1 Issue 1: Leaving PM2 or PM3 can Produce Glitches on the SCL and SDA Pins

Glitches can occur on the SCL and SDA pins when leaving PM2 or PM3.

1.1.1 Issue Description

The I2C pins SCL and SDA must be high impedance with pull-up when not transmitting on the I2C bus. This issue can cause a low pulse for approximately 250 ns when going from PM2 or PM3 to active mode. This is due to an insufficient reset of the I2C module when exiting PM2 or PM3.

1.1.2 Suggested Workarounds

To prevent these glitches, the I2C pin override bit (I2CWC.OVR) can be set before entering PM2. This bit overrides the I2C module control of the I/O lines and sets them to the state defined in I2CWC. The I/O lines should then be left in the reset state for I2CWC, which is input with pull-up enabled. The I2CWC.OVR bit can be cleared just after returning to active mode, preventing any glitches from propagating to the pins.
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